



Product Change Notification: MFOL-190LWR204

Date:

26-May-2026

Product Category:

Current And Power Measurement Ics

Notification Subject:

CCB 8147 Initial Notice: Qualification of UAT as an additional bumping site and UNIS as an additional Backend Process (BE2) for PAC1931T-I/J6CX, PAC1934T-I/J6CX, PAC1933T-I/J6CX, PAC1932T-I/J6CX, PAC1941T-1E/J6CX, PAC1941T-2E/J6CX, PAC1942T-1E/J6CX, PAC1942T-2E/J6CX, PAC1943T-E/J6CX, PAC1944T-E/J6CX, PAC1951T-1E/J6CX, PAC1951T-2E/J6CX, PAC1952T-1E/J6CX, PAC1952T-2E/J6CX, PAC1953T-E/J6CX, PAC1954T-E/J6CX catalog part numbers (CPN) available in 16L WLCSP (2.215x2.16x0.7mm) package.

Affected CPNs:

[MFOL-190LWR204_Affected_CPN_05262026.pdf](#)

[MFOL-190LWR204_Affected_CPN_05262026.csv](#)

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of UAT as an additional bumping site and UNIS as an additional Backend Process (BE2) for PAC1931T-I/J6CX, PAC1934T-I/J6CX, PAC1933T-I/J6CX, PAC1932T-I/J6CX, PAC1941T-1E/J6CX, PAC1941T-2E/J6CX, PAC1942T-1E/J6CX, PAC1942T-2E/J6CX, PAC1943T-E/J6CX, PAC1944T-E/J6CX, PAC1951T-1E/J6CX, PAC1951T-2E/J6CX, PAC1952T-1E/J6CX, PAC1952T-2E/J6CX, PAC1953T-E/J6CX, PAC1954T-E/J6CX catalog part numbers (CPN) available in 16L WLCSP (2.215x2.16x0.7mm) package.

Pre and Post Summary Changes:

	Pre Change	Post Change
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Bumping Site	ASE Inc. (ASEB)	ASE Inc. (ASEB)	Unisem Advance Tech (UAT)
Back End Process	ASE Test (ASE9)	ASE Test (ASE9)	Unisem (M) Berhad Perak, Malaysia (UNIS)
Solder Ball Material	SAC405	SAC405	SAC405
Polymer Material	PI	PI	PI

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve on-time delivery performance by qualifying UAT as an additional bumping site and UNIS as an additional Backend Process (BE2).

Change Implementation Status: In Progress

Estimated Qualification Completion Date: August 2026

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

	March 2026					>	August 2026				
Work Week	10	11	12	13	14		32	33	34	35	36
Initial PCN Issue Date				X							
Qual Report Availability										X	
Final PCN Issue Date										X	

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: March 23, 2026: Issued initial notification.

May 26, 2026: Re-issued initial notification to update the MP Code (MPC) in the Qualification Plan.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_MFOL-190LWR204_Qualification Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN):

PAC1931T-I/J6CX
PAC1934T-I/J6CX
PAC1933T-I/J6CX
PAC1932T-I/J6CX
PAC1941T-1E/J6CX
PAC1941T-2E/J6CX
PAC1942T-1E/J6CX
PAC1942T-2E/J6CX
PAC1943T-E/J6CX
PAC1944T-E/J6CX
PAC1951T-1E/J6CX
PAC1951T-2E/J6CX
PAC1952T-1E/J6CX
PAC1952T-2E/J6CX
PAC1953T-E/J6CX
PAC1954T-E/J6CX



QUALIFICATION PLAN SUMMARY

PCN #: MFOL-19OLWR204

**Date:
May 21, 2026**

Qualification of UAT as an additional bumping site and UNIS as an additional Backend Process (BE2) for PAC1931T-I/J6CX, PAC1934T-I/J6CX, PAC1933T-I/J6CX, PAC1932T-I/J6CX, PAC1941T-1E/J6CX, PAC1941T-2E/J6CX, PAC1942T-1E/J6CX, PAC1942T-2E/J6CX, PAC1943T-E/J6CX, PAC1944T-E/J6CX, PAC1951T-1E/J6CX, PAC1951T-2E/J6CX, PAC1952T-1E/J6CX, PAC1952T-2E/J6CX, PAC1953T-E/J6CX, PAC1954T-E/J6CX catalog part numbers (CPN) available in 16L WLCSP (2.215x2.16x0.7mm) package.



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Package Qualification Plan

Purpose: Qualification of UAT as an additional bumping site and UNIS as an additional Backend Process (BE2) for PAC1931T-I/J6CX, PAC1934T-I/J6CX, PAC1933T-I/J6CX, PAC1932T-I/J6CX, PAC1941T-1E/J6CX, PAC1941T-2E/J6CX, PAC1942T-1E/J6CX, PAC1942T-2E/J6CX, PAC1943T-E/J6CX, PAC1944T-E/J6CX, PAC1951T-1E/J6CX, PAC1951T-2E/J6CX, PAC1952T-1E/J6CX, PAC1952T-2E/J6CX, PAC1953T-E/J6CX, PAC1954T-E/J6CX catalog part numbers (CPN) available in 16L WLCSP (2.215x2.16x0.7mm) package.

CCB No.: 8147

Misc.	Assembly site	Bump: UAT Back End Process (BE2): UNISEM
	MP Code (MPC)	VA7B1Y6CXB22
	Part Number (CPN)	PAC1952T-2E/J6CX
	MSL information	MSL-1
	Assembly Shipping Media (T/R, Tube/Tray)	T/R
	Base Quantity Multiple (BQM)	5000
PKG	Package Type	WLCSP
	Pin/Ball Count	16
	PKG width/size	2.215x2.16
	Solder Ball Material	SAC405
	Solder Ball Pitch/Size	500/300
	Polymer Material	PI
	Polymer Thickness	7.5
	UBM Deposition Method	sputter/plated
	UBM Thickness	Ti(0.12)/Cu(0.2) + plated Cu(8.6)
	UBM Opening Diameter	300um
	RDL Deposition method	sputter/plated
	RDL Thickness	Ti(0.12)/Cu(0.2) + plated Cu(6)

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	# of CSP lots	Total Units	Fail Accept Qty	Est. Dur. Days	Special Instruction
Moisture Sensitivity	JESD22-A113. +150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020E for package type; Electrical test pre and post stress at +25°C. (MSL-1, 260C)	77 dice	5	3	82	0	15	Spares should be properly identified.
HAST, Unbiased	JESD22-A118. +130°C/85% RH for 96 hours. Electrical test pre and post stress at 25°C. OR +110°C/85% RH for 264 hours. Electrical test pre and post stress at 25°C.	77 dice	5	3	82	0	10	Spares should be properly identified.
Temp Cycle	JESD22-A104. -65°C to +150°C for 500 cycles or -40°C to 125°C for 1000 cycles. Electrical test pre and post stress at +25°C (required) and hot temp (optional). Read points at 0, 500, and 1000 (if applicable) cycles.	77 dice	5	3	82	0	15	Spares should be properly identified.
High Temperature Storage	Tested per JESD22-A103. 150°C storage for 1000hrs or 175°C storage for 500 hrs. Electrical test pre and post stress at 25°C.	45 dice	5	1	50	0	50	Spares should be properly identified.
High Temp Bake and Low Speed Ball Shear	Tested per JESD22-B117 Bake conditions 150°C for 1000hrs or 175°C for 500hrs. Low speed shear per condition A or high-speed shear per condition B	30 shears	0	1	35	0		Spares should be properly identified.